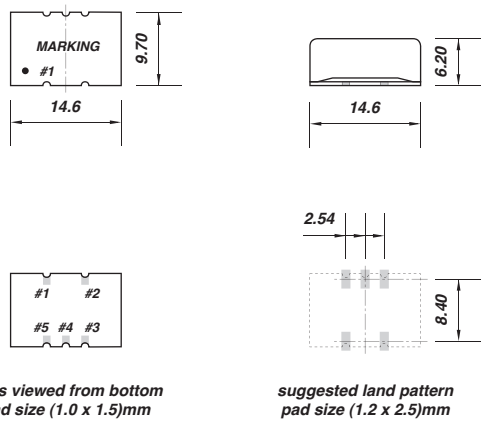
Sub-miniature precision hybrid smd OCXO

Temperature tolerance: ±0.1ppm(-5 +70)°C
Low profile smd package
Good phase noise
AT cut crystal
+3.3V d.c. supply
Fast warm up
RoHS compliant

Generic specification:

frequency:	*(10 ~ 40)MHz*
output:	*clipped sine wave*
	0.8Vp/p min., 10KΩ//10pF
stability:	
against temperature	*±0.1ppm(-5 +70)°C*
against supply voltage change	*±0.02ppm max., V_{cc} ±5%*
against load change	*±0.02ppm max., load ±10%*
ageing short term	*±0.003ppm max. per day after 30 days continuous operation*
ageing long term	*±1.0ppm max. per year after 30 days continuous operation*
voltage trim V_t	*±5ppm minimum, ±10ppm typical +1.5Vd.c. ±1.5Vd.c. linearity ±5%*
trim input impedance	*100KΩ min.*
power supplies:	
supply voltage V_{cc}	*+3.3Vd.c.*
voltage reference	*+3Vd.c.*
start up current	*750mA max. at -5°C*
quiescent current	*320mA max. at +25°C*
warm up time	*2 minutes max. to within 0.5ppm of nominal*
insulation resistance	*500MegΩ min., 100Vd.c.*
phase noise:	*-120dBc/Hz, f_o+100Hz*
	-130dBc/Hz, f_o+1kHz
	-140dBc/Hz, f_o+10kHz
temperature:	
operating range	*(-5 +70)°C*
storage range	*(-40 +125)°C*
marking:	*part number, frequency, date code, serial number*

Dimensions(mm):



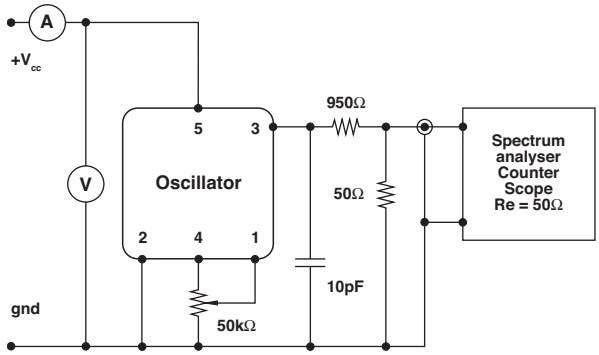
pads viewed from bottom pad size (1.0 x 1.5)mm

suggested land pattern pad size (1.2 x 2.5)mm

Pin connections:

# 1	*tune*
# 2	*ground/ case*
# 3	*output*
# 4	*V_{ref} or N/C*
# 5	*+V_{cc}*

Test circuit, CMOS load:



test circuit includes a 20:1 step down into a matched 50Ω load

Environmental conditions:

MIL standard 202F	*method 213, condition J*
MIL standard 202F	*method 107, condition A*
MIL standard 202F	*method 204, condition B*
solderability	*5 seconds max. at +230°C*
	3 seconds max. at +350°C

Telephone: +1 905 623 4101, Fax: +1 905 623 3886
e-mail: sales@laptech.com website: www.laptech.com